XL-504SYGC F5 技术数据表

特点（

目录

Catalogue

Catalogue

电性参数

亮度分档

代码	最小值	最大值	单位	测试条件
A4	300	400	mcd	IF=20mA
A5	400	500		
A6	500	700		

电压分档

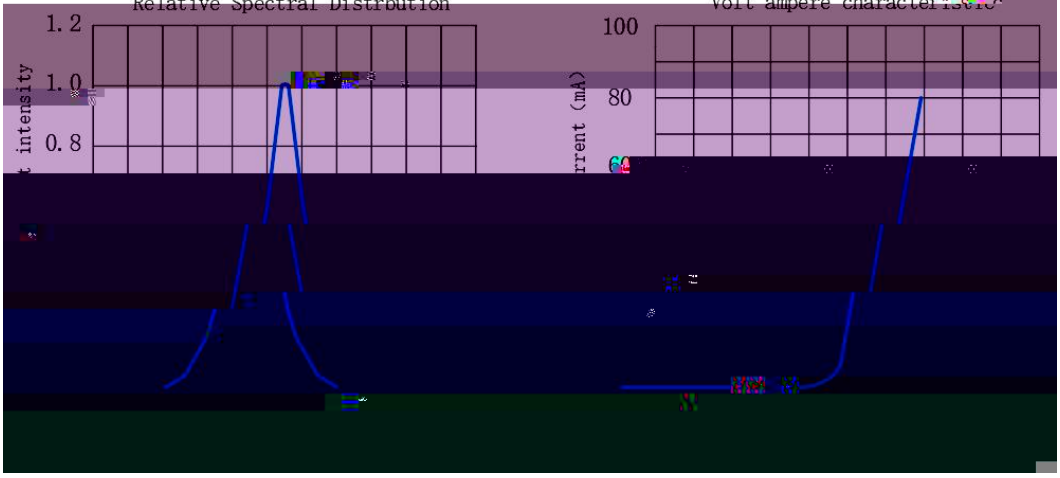
代码	最小值	最大值	单位	测试条件
N12-8	2.0	2.2	V	IF=20mA
N12-9	2.2	2.4		
N13-1	2.4	2.6		

波长分档

代码		最大值	单位	
HYG03	565	567.5	nm	IF=20mA
HYG04	567.5	570		
HYG05	570	572.5		
HYG06	572.5	575		

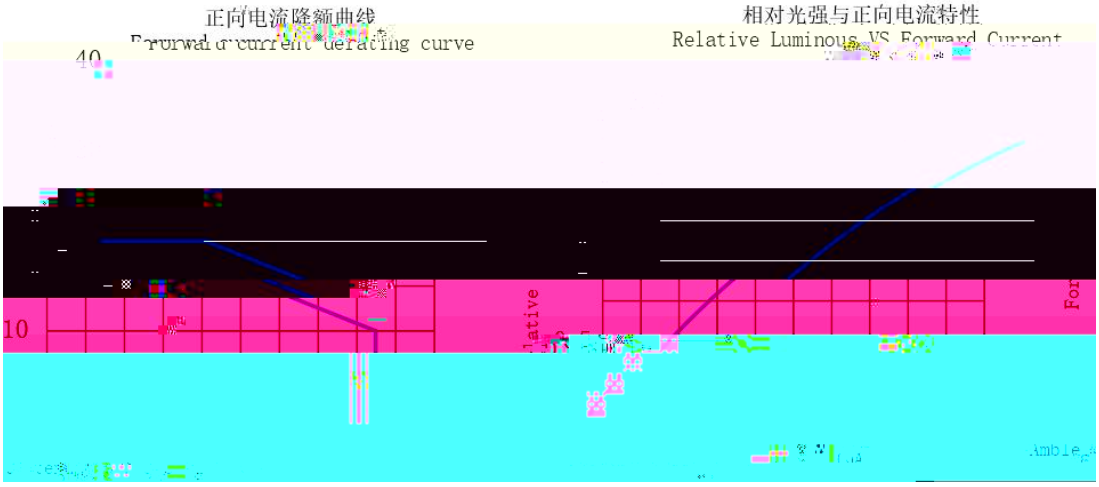
典型特性曲线

光谱分布曲线
Relative Spectral Distrbution



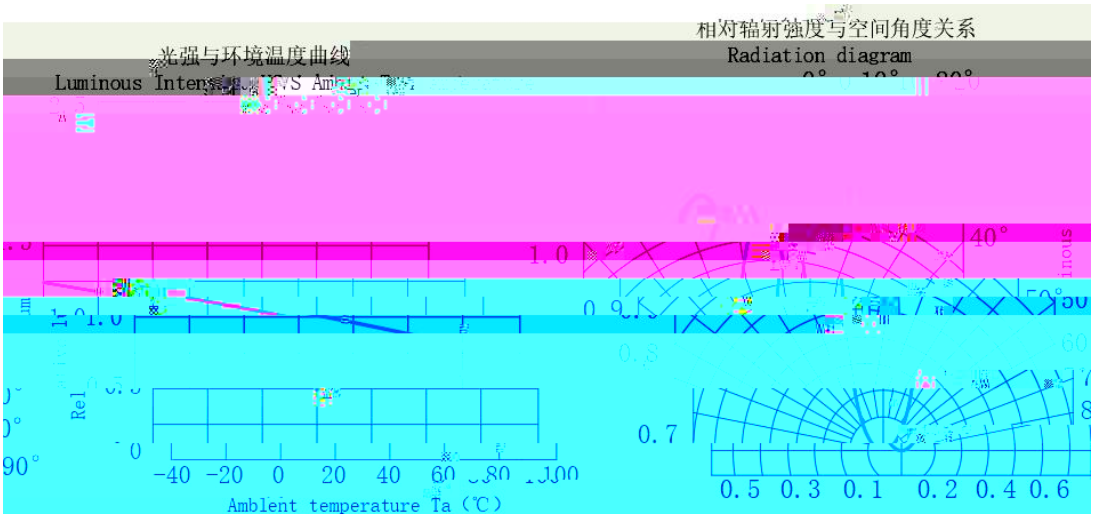
伏安特性
Volt ampere characteristic

正向电流降额曲线
Forward current derating curve



相对光强与正向电流特性
Relative Luminous VS Forward Current

光强与环境温度曲线
Luminous Intensity VS Ambient Temperature



相对辐射强度与空间角度关系
Radiation diagram

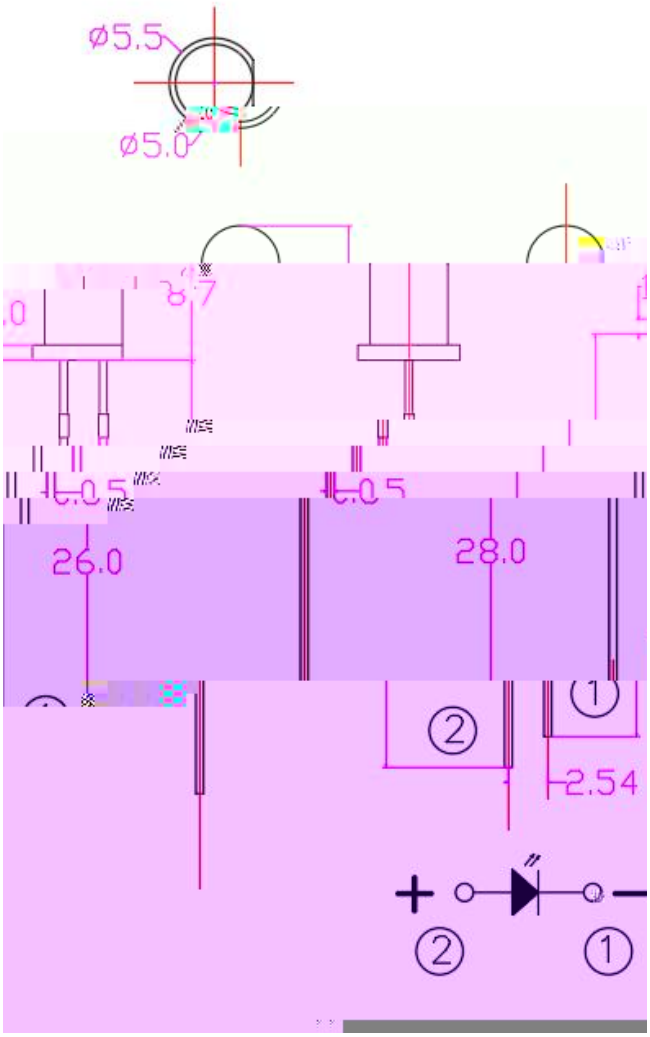
25±5 /Note If not otherwise indicated the test environment temp erature is 25±5

可靠性试验

Reliability Test Items And Conditions

Class	Test item	Testing environment	Testing time	Qty	Fail qty

外形尺寸



(Note)

Dimensions are in millimeters.

± 0.50

Tolerances unless mentioned are ± 0.50mm.

使用注意事项（ ）

1. [redacted]
LED

This LED can be used in some ordinary electronic equipment, such as office equipment, communication equipment, house decoration, if LED is used in some high reliability requirements, such as air transportation, traffic control and medical liao equipment, must refer to the information provided by sales.

Storage environment of LED with temperature not exceeding 30 and relative humidity not exceeding 70%.It is recommended that LDE be used in the original box for no more than three months. If longer storage time is required, put it in the drying box and add desiccant or filled with nitrogen.

Special care must be taken when cleaning colloids with chemicals, as some chemicals have damage to the colloidal surface and cause fading such as trichloroethylene, propylene, ketone, etc.It can be wiped and soaked with ethanol for no more than 3 minutes at room temperature.

1 2
It must be 2 mm from the colloid to bend the bracket.
2
Support forming must be done with fixtures or by a professional.
3
Support forming must be completed before welding.
4
The pins and spacing are the same as on the circuit board.
5 PCB LED

XCG

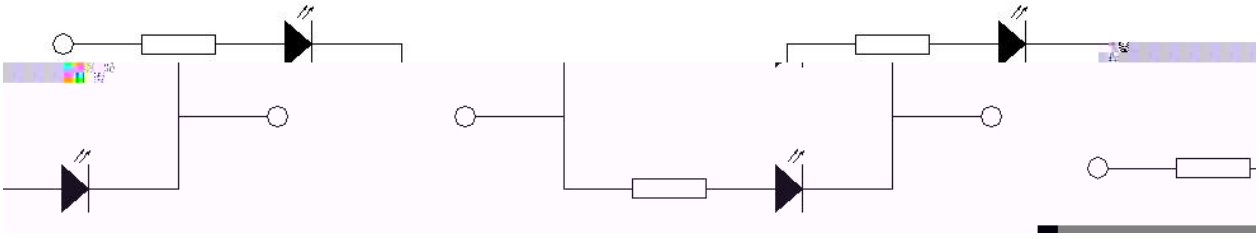
使用注意事项（ ）

2mm

When welding, welding must be conducted below 2mm of colloid bottom. When welding, try to avoid soaking LED colloid. After welding, avoid adding external force on the pin or shaking LED colloid.

LED LED A LED LED

In the current driving mode of LED, if LED is multiple in parallel, it is recommended to use line A and add a flow limit resistance to each LED to ensure the consistent brightness of LED.



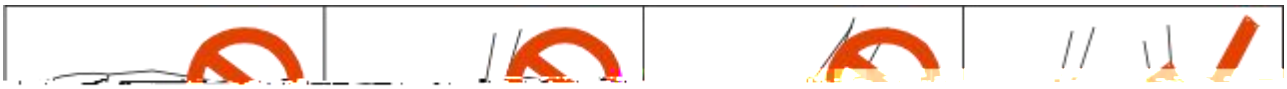
LED InGaN
HBM<1000V <100V

High increase of static electricity and current will damage LED. Use antistatic devices such as protective belts and gloves. Note: human discharge mode HBM <1000V; machine discharge mode <100V.

使用注意事项（ ）

8、其他事项：

When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



LED

The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.

9、眼睛保护忠告：

LED LED

Viewing direct to the light emitting center of the LEDs, especially those of great Luminous Intensity, will cause great hazard to human eyes. Please be careful.

If there are any modifications to the specification